

RX18 NO CLEAN CORED WIRE SOLDER

FEATURES

- Low Voids/Skips
- Low Spatter
- Extends Solder Tip Life
- ROL0 per IPC J-STD-004
- REACH and RoHS Compliant*
- Fast Wetting/Feed Rates

DESCRIPTION

RX18 no clean flux core wire solder was developed to provide excellent soldering results with all alloys and surface finishes. Engineered for robotic soldering, RX18 promotes thermal transfer, fast wetting and rapid solder penetration into plated through holes or surface mount interconnections. RX18 specialized packaging ensures consistent, accurate, jam-free wire feeding. RX18 post solder residues are minimal, clear and pass IPC-004A and IPC-004B SIR and corrosion requirements and do not require cleaning.

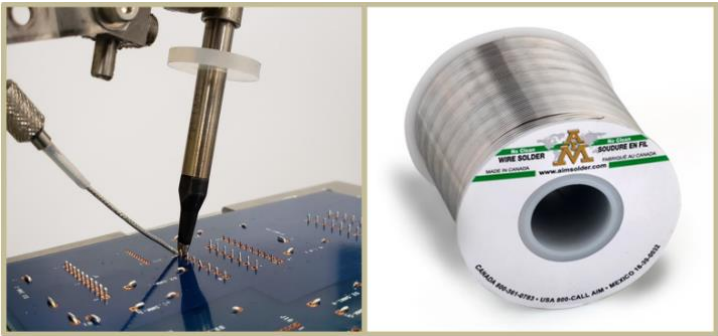
STANDARD AVAILABILITY

RX18 is available in multiple lead-free alloys. Additional alloys and diameters may be available upon request.

APPLICATION

Best results are obtained with properly sized solder iron tip with a temperature between 300° - 400°C (575° - 750°F) for leaded alloys and 370° - 425°C (700° - 800°F) for lead-free alloys.

*Lead-free.



HANDLING & STORAGE

Time	Parameters
7 Years	< 85°F (< 29°C)

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.

CLEANING

RX18 can be cleaned with commercially available flux removers. IPA is not recommended. Contact AIM for specific information.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

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TEST DATA SUMMARY

NAME	TEST METHOD	RESULTS	
IPC Flux Classification	J-STD-004	ROLO	
IPC Flux Classification	J-STD-004B 3.3.1	ROL1	
NAME	TEST METHOD	TYPICAL RESULTS	IMAGE
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	0.09% Typical	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	PASS
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	PASS	Log SIR (Ohm) Time, day Legend: RX18 1A, RX18 1B, RX18 1C, RX18 1D, RX18 2A, RX18 2B, RX18 2C, RX18 2D, CONTROL 1A, CONTROL 1B, CONTROL 1C, CONTROL 1D
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	156 mg KOH/g flux Typical	

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